HSF

NOTE:

1.MATERIAL:
- 1.1 INSULATOR: LCP+30%G.F, UL94V-0; BLACK.
- 1.2 CAP: LCP+30%G.F, UL94V-0; BLACK.
- 1.3 CONTACT: PHOSPHOR BRONZE.
- 1.4 MOUNTING EAR: PHOSPHOR BRONZE.

2.FINISH:
- 2.1 CONTACT: 3u" OR 5u" MIN. GOLD PLATED IN CONTACT AREA
  △ 80u" MIN. TIN PLATED IN SOLDER AREA
  50u" MIN. NICKEL UNDERPLATED OVERALL.
- 2.2 MOUNTING EAR: 100u" MIN. TIN PLATED OVER
  50u" MIN. NICKEL UNDERPLATED OVERALL.

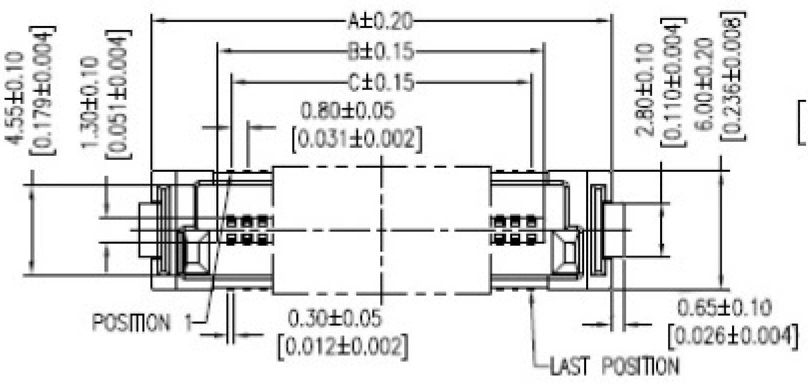
3.ELECTRICAL CHARACTERISTICS
- 3.1 CURRENT RATING: 0.5A.
- 3.2 CONTACT RESISTANCE: 65mΩ MAX.
- 3.3 INSULATION RESISTANCE: 1000MΩ MIN DC500V.
- 3.4 DIELECTRIC WITHSTANDING VOLTAGE: 250V AC PER MINUTE.
- 3.5 OPERATING TEMPERATURE: -40°C ~ +105°C.
- 3.6 OPERATING: 100 CYCLES MIN.
- 3.7 INSERTION FORCE: 90g MAX. Per PIN Pair.
- 3.8 WITHDRAWAL FORCE: 10g MIN. Per PIN Pair.
- 3.9 CONTACT RETENTION FORCE: 250g MIN. PER CONTACT
- 3.10 STORAGE TEMPERATURE: -10°C ~ +40°C.

Flatness: <80Pins The "M" Is 0.10mm MAX
△ ≥80Pins The "M" Is 0.15mm MAX

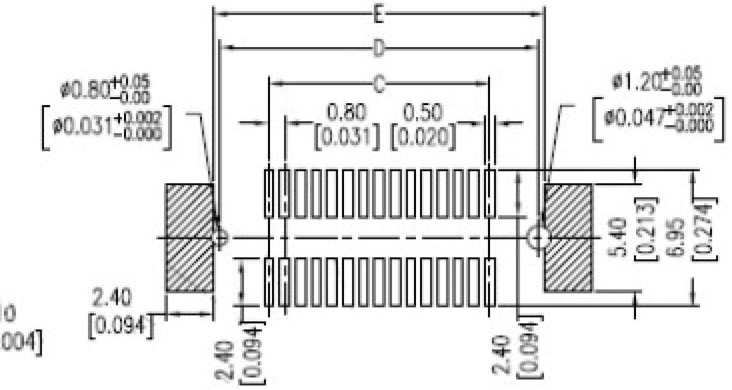
Ordering Information

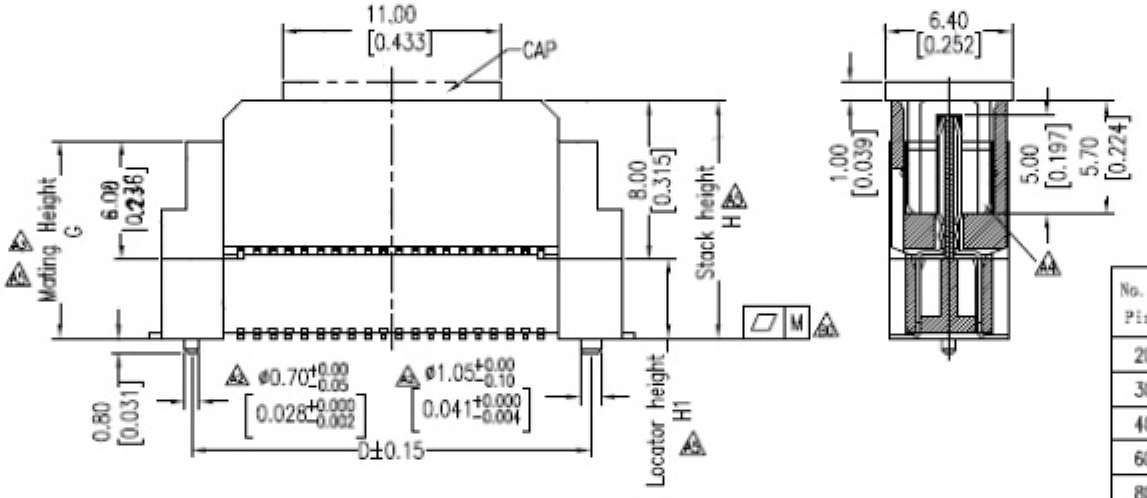
3614- P XXX - XXX XX R 01

XXX	XXX	XX	R
No.of Pins	High "H"	Contact Plating	Packing
		△ S1=3u"Gold/Tin S2=5u"Gold/Tin	R=Tape&Reel+CAP



Recommended P.C.B Layout (Top Side)
(PCB BOARD TOLERANCE ± 0.05)





△

Dim H	Dim G	Dim H1
8.00	6.00	---
11.00	9.00	3.00
12.00	10.00	4.00
13.00	11.00	5.00
14.00	12.00	6.00

No. of Pins	Dimension				
	A	B	C	D	E
20	15.30	8.60	7.20	12.20	12.80
30	19.30	12.60	11.20	16.20	16.80
40	23.30	16.60	15.20	20.20	20.80
60	31.30	24.60	23.20	28.20	28.80
80	39.30	32.60	31.20	36.20	36.80
100	47.30	40.60	39.20	44.20	44.80
120	55.30	48.60	47.20	52.20	52.80
160	71.30	64.60	63.20	68.20	68.80

REV	DATE	MODIFICATION DESCRIPTION	CHANGE
B0	2013/06/26	ADD NEW PLATED TYPE	△
A5	2012/07/23	MODIFY	△
A4	2011/10/19	CHANG THE CAP	△
A0	2010/03/09	NEW	—

OPERATION	
X.X	±0.40
X.XX	±0.25
X.XXX	±0.15
Angle	± 3'
DIM	TOL

DRAW Tsingsn	DATE 2013/06/26
CHECK	DATE
APPROVE	DATE

SCALE	FIT
UNIT	~~mm~~ inch
SIZE	A4
SHEET	1/1
PROJ.	⌖◁

PART NO. SM C06 3614 P

TITLE:
0.80mm BTB MALE
"D" TYPE 180° SMT

Customer NO.

SCHMID-M